

IN THE SPECIFICATION

On page 1, first line, please insert -- This is a Continuation Application of Serial No. 09/968,466, filed September 28, 2001, which is presently pending. --

On page 6, line 19, please delete the second sentence in paragraph 17 in its entirety and insert --- In one embodiment, the anode **170** may be located towards the periphery of the wafer carrier **180** if a surface layer on the wafer is continuous and conductive. --- therein.

On page 6, line 28, please delete the third sentence in paragraph 18 in its entirety and insert --- The wafer carrier **180** can vary the pressure of the wafer **160** on the polishing pad **120** and the slurry **150**. --- therein.